

Tz-Cheng Chiu

List of Publications by Year in descending order

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28
papers

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| # | ARTICLE | IF | CITATIONS |
|----|---|-----|-----------|
| 1 | Development and Application of the Moisture-Dependent Viscoelastic Model of Polyimide in Hygro-Thermo-Mechanical Analysis of Fan-Out Interconnect. , 2022, , . | | 2 |
| 2 | A unified viscoplastic model for characterizing the softening behavior of the Sn3.0Ag0.5Cu solder under monotonic and cyclic loading conditions. Microelectronics Reliability, 2021, 119, 114086. | 1.7 | 6 |
| 3 | A Mechanics Model for the Moisture Induced Delamination in Fan-Out Wafer-Level Package. , 2020, , . | | 8 |
| 4 | A Viscoplastic-Based Fatigue Reliability Model for the Polyimide Dielectric Thin Film. , 2019, , . | | 3 |
| 5 | Coupled Hygro-Thermo-Mechanical Analysis of Moisture Induced Interfacial Stresses in Fan-Out Package. , 2019, , . | | 5 |
| 6 | Warpage simulation for the reconstituted wafer used in fan-out wafer level packaging. Microelectronics Reliability, 2018, 80, 14-23. | 1.7 | 47 |
| 7 | Thermo-mechanical analysis of laser peeling of ultrathin glass for removing edge flaws in web processing applications. Microsystem Technologies, 2018, 24, 397-409. | 2.0 | 6 |
| 8 | Fatigue Crack Growth on the Interface of Copper and Epoxy Molding Compound under Mixed-Mode Loading. , 2018, , . | | 0 |
| 9 | An experimental setup for characterizing subcritical debonding of materials interface under mixed mode fatigue loading. International Journal of Fatigue, 2018, 114, 109-119. | 5.7 | 3 |
| 10 | Physical Aging of Epoxy Molding Compound and Its Influences on the Warpage of Reconstituted Wafer. , 2018, , . | | 5 |
| 11 | Development of consistent interconversions between linear viscoelastic functions for multiaxial viscoelastic models. , 2017, , . | | 0 |
| 12 | A Novel Experimental System for Characterizing Interface Delamination under Mixed-Mode Fatigue Loading. , 2016, , . | | 0 |
| 13 | On the mechanics of laser peeling for ultra-thin glasses. Engineering Fracture Mechanics, 2016, 163, 236-247. | 4.3 | 8 |
| 14 | Time-domain viscoelastic constitutive model based on concurrent fitting of frequency-domain characteristics. Microelectronics Reliability, 2015, 55, 2336-2344. | 1.7 | 4 |
| 15 | Analysis of fatigue delamination growth in flip-chip package. Acta Mechanica, 2014, 225, 2761-2773. | 2.1 | 6 |
| 16 | Using DMA to Simultaneously Acquire Young's Relaxation Modulus and Time-dependent Poisson's Ratio of a Viscoelastic Material. Procedia Engineering, 2014, 79, 153-159. | 1.2 | 12 |
| 17 | Simultaneously obtaining the Young's relaxation modulus and shear relaxation modulus of an epoxy molding compound by using DMA. , 2014, , . | | 0 |
| 18 | Evaluation of Strain Measurement in a Die-to-Interposer Chip Using In Situ Synchrotron X-Ray Diffraction and Finite-Element Analysis. Journal of Electronic Materials, 2014, 43, 52-56. | 2.2 | 2 |

| # | ARTICLE | IF | CITATIONS |
|----|--|-----|-----------|
| 19 | Temperature distribution and heat flow around a crack of arbitrary orientation in a functionally graded medium. <i>Journal of Engineering Mathematics</i> , 2014, 87, 123-137. | 1.2 | 7 |
| 20 | A numerical procedure for simulating delamination growth on interfaces of interconnect structures. <i>Microelectronics Reliability</i> , 2012, 52, 1464-1474. | 1.7 | 4 |
| 21 | Warpage evolution of overmolded ball grid array package during post-mold curing thermal process. <i>Microelectronics Reliability</i> , 2011, 51, 2263-2273. | 1.7 | 17 |
| 22 | Effects of Curing and Chemical Aging on Warpage Characterization and Simulation. <i>IEEE Transactions on Device and Materials Reliability</i> , 2011, 11, 339-348. | 2.0 | 20 |
| 23 | Reliability model for bridging failure of Pb-free ball grid array solder joints under compressive load. <i>Microelectronics Reliability</i> , 2010, 50, 2037-2050. | 1.7 | 7 |
| 24 | Ball Grid Array Solder Joint Reliability Under System-Level Compressive Load. <i>IEEE Transactions on Device and Materials Reliability</i> , 2010, 10, 324-337. | 2.0 | 13 |
| 25 | Analysis of stress intensity factors for three-dimensional interface crack problems in electronic packages using the virtual crack closure technique. <i>International Journal of Fracture</i> , 2009, 156, 75-96. | 2.2 | 33 |
| 26 | On the Homogenization of Multilayered Interconnect for Interfacial Fracture Analysis. <i>IEEE Transactions on Components and Packaging Technologies</i> , 2008, 31, 388-398. | 1.3 | 7 |
| 27 | Three dimensional corner delamination analysis for fan-out chip scale package. , 2008, , . | | 2 |
| 28 | Analysis of flip-chip corner delamination using 3-D virtual crack closure technique. , 2008, , . | | 0 |